## 8-Input Data Selector/ **Multiplexer** with **3-State Outputs**

## **High-Performance Silicon-Gate CMOS**

The MC54/74HC251 is identical in pinout to the LS251. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device selects one of the eight binary Data Inputs, as determined by the Address Inputs. The Output Enable pin must be a low level for the selected data to appear at the outputs. If Output Enable is high, both the Y and the  $\overline{Y}$  outputs are in the high-impedance state. This 3-state feature allows the HC251 to be used in bus-oriented systems.

The HC251 is similar in function to the HC251 which does not have 3-state outputs.

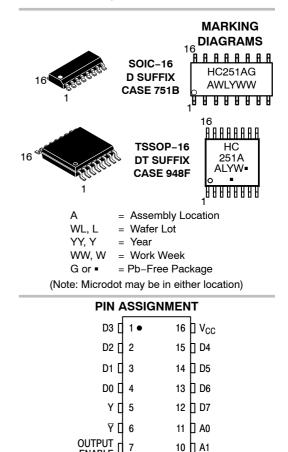
#### **Features**

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- These are Pb-Free Devices



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#### **ORDERING INFORMATION**

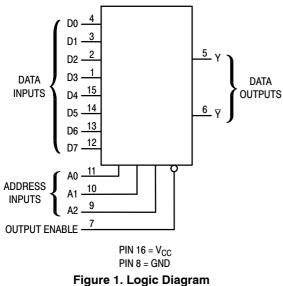
10 🗍 A1

9 Π A2

7

ENABLE GND 8

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.



#### **FUNCTION TABLE**

	Inputs				outs
A2	A1	A0	Output Enabled	Y	Ŷ
XLLLHHHH	X L L H H L L H H	X L H L H L H L H	H L L L L L L	Z D0 D1 D2 D3 D4 D5 D6 D7	Z D0 D1 D2 D3 D4 D5 D6 D7

Z = high impedance

D0, D1, ..., D7 = the level of the respective D input.

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	DC Supply Voltage (Referenced to	-0.5 to + 7.0	V	
V <sub>in</sub>	DC Input Voltage (Referenced to	GND)	–1.5 to V <sub>CC</sub> + 1.5	V
V <sub>out</sub>	DC Output Voltage (Referenced to	o GND)	–0.5 to V <sub>CC</sub> + 0.5	V
l <sub>in</sub>	DC Input Current, per Pin	±25	mA	
l <sub>out</sub>	DC Output Current, per Pin	±50	mA	
I <sub>CC</sub>	DC Supply Current, $V_{CC}$ and GNI	DC Supply Current, $V_{CC}$ and GND Pins		mA
P <sub>D</sub>	Power Dissipation in Still Air SOIC Package TSSOP Package		500 TBD	mW
T <sub>stg</sub>	Storage Temperature		-65 to + 150	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>in</sub> and Vout should be constrained to the range GND  $\leq$  (V<sub>in</sub> or V<sub>out</sub>)  $\leq$  V<sub>CC</sub>.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter			Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)		2.0	6.0	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Figure 2)	$V_{CC} = 2.0 V$ $V_{CC} = 4.5 V$ $V_{CC} = 6.0 V$	0 0 0	1000 500 400	ns

	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit			
Symbol				- 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage	$\begin{array}{l} V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V} \\  I_{out}   \leq  20 \; \mu\text{A} \end{array}$	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	$\begin{array}{l} V_{out} = 0.1 \ V \ or \ V_{CC} - 0.1 \ V \\  I_{out}  \ \leq \ 20 \ \mu A \end{array}$	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1.2	V
V <sub>OH</sub>	Minimum High-Level Output Voltage		2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$\begin{array}{ll} V_{in} = V_{IH} \text{ or } V_{IL} & \left I_{out}\right  \leq 4.0 \text{ mA} \\ \left I_{out}\right  \leq 5.2 \text{ mA} \end{array}$	4.5 6.0	3.98 5.48	3.84 5.34	3.70 5.20	
V <sub>OL</sub>	Maximum Low-Level Output Voltage		2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$ \begin{array}{ll} V_{in} = V_{IH} \text{ or } V_{IL} & \left  I_{out} \right  \leq 4.0 \text{ mA} \\ \left  I_{out} \right  \leq 5.2 \text{ mA} \end{array} $	4.5 6.0	0.26 0.26	0.33 0.33	0.40 0.40	
l <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	± 0.1	± 1.0	± 1.0	μA
I <sub>OZ</sub>	Maximum Three-State Leakage Current	Output in High-Impedance State $V_{in} = V_{IL} \text{ or } V_{IH}$ $V_{out} = V_{CC} \text{ or GND}$	6.0	± 0.5	± 5.0	± 10	μΑ
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC} \text{ or GND}$ $I_{out} = 0 \ \mu A$	6.0	8	80	160	μA

## DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

			Guaranteed Limit			
Symbol	Parameter	V <sub>CC</sub> V	- 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Input D to Output Y or ▼ (Figures 2, 3 and 6)	2.0 4.5 6.0	185 37 31	230 46 39	280 56 48	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Input A to Output Y or $\overline{Y}$ (Figures 3 and 6)	2.0 4.5 6.0	205 41 35	255 51 43	310 62 53	ns
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Maximum Propagation Delay, Output Enable to Output Y (Figures 5 and 7)	2.0 4.5 6.0	195 39 33	245 49 42	295 59 50	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	Maximum Propagation Delay, Output Enable to Output Y (Figures 5 and 7)	2.0 4.5 6.0	145 29 25	180 36 31	220 44 38	ns
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Maximum Propagation Delay, Output Enable to Output $\overline{Y}$ (Figures 5 and 7)	2.0 4.5 6.0	220 44 37	275 55 47	330 66 56	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	Maximum Propagation Delay, Output Enable to Output $\overline{Y}$ (Figures 5 and 7)	2.0 4.5 6.0	150 30 26	190 38 33	225 45 38	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 2 and 6)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C <sub>in</sub>	Maximum Input Capacitance	-	10	10	10	pF
C <sub>out</sub>	Maximum Three-State Output Capacitance (Output in High-Impedance State)	-	15	15	15	pF

#### **AC ELECTRICAL CHARACTERISTICS** ( $C_L = 50 \text{ pF}$ , Input $t_r = t_f = 6 \text{ ns}$ )

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (Per Package)	36	pF

#### **PIN DESCRIPTIONS**

#### INPUTS

#### D0, D1, ..., D7 (Pins 4, 3, 2, 1, 15, 14, 13, 12)

Data inputs. Data on one of these eight binary inputs may be selected to appear on the output.

#### **CONTROL INPUTS**

#### A0, A1, A2 (Pins 11, 10, 9)

Address inputs. The data on these pins are the binary address of the selected input (see the Function Table).

#### Output Enable (Pin 7)

Output Enable. This input pin must be at a low level for the selected data to appear at the outputs. If the Output Enable pin is high, both the Y and  $\overline{Y}$  outputs are taken to the high–impedance state.

#### OUTPUTS

#### Y, Y (Pins 5, 6)

Data outputs. The selected data is presented at these pins in both true (Y output) and complemented ( $\overline{Y}$  output) forms.

### SWITCHING WAVEFORMS

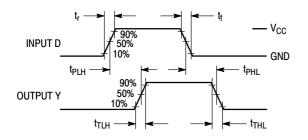
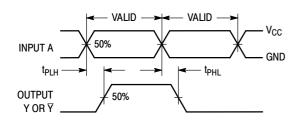
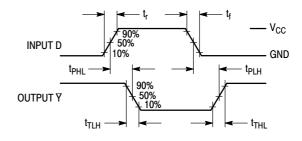


Figure 2.









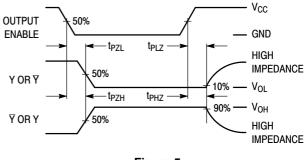
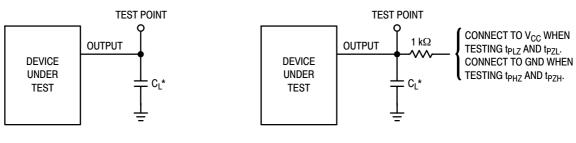


Figure 5.



## **TEST CIRCUITS**



\*Includes all probe and jig capacitance

Figure 6.

\*Includes all probe and jig capacitance

Figure 7.

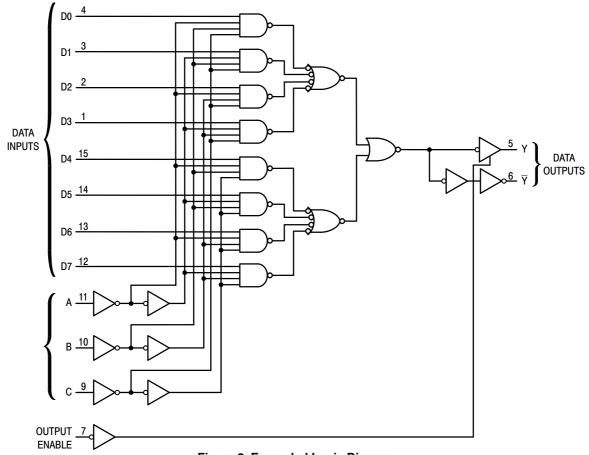


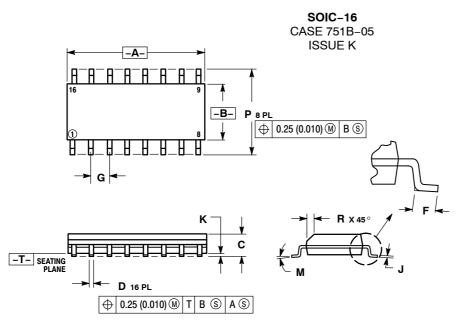
Figure 8. Expanded Logic Diagram

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74HC251ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC251ADR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74HC251ADTR2G	TSSOP-16*	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
\*This package is inherently Pb-Free.

#### PACKAGE DIMENSIONS



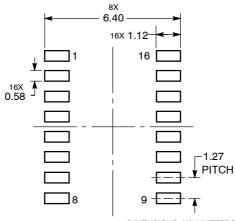
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD DIDATELISION

4 5

DIMENSIONS A AND & DO NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

**SOLDERING FOOTPRINT\*** 



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

MIN MAX

0.026 BSC

0.007 0.011

0.004 0.008

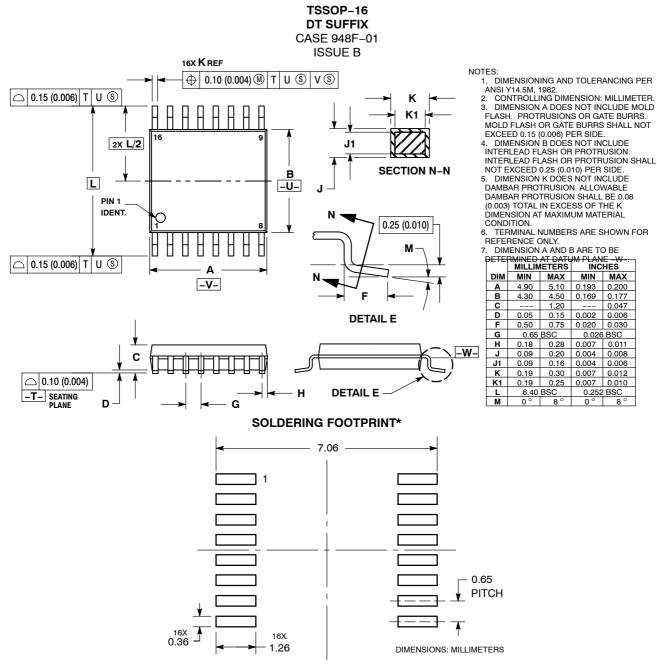
0.252 BSC

8

0

8

5.10 0.193 0.200



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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